# Minutes of WP-meeting 230

### Attendance:

DESY: Ties Behnke, Ralf Diener, Ulrich Einhaus, Oleksiy Fedorchuk, Leif Jönsson, Claus Kleinwort, Paul Malek, Felix Müller, Volker Prahl, Oliver Schäfer, Dimitra Tsionou, Annika Vauth Fuzebox: Keisuke Fujii, Serguei Ganjour, Katsumasa Ikematsu, Jochen Kaminski, Takeshi Matsuda, Amir Shirazi, Ron Settles, Akira Sugiyama, Junping Tian, Jan Timmermans

### **General News:**

Ties explained that Hitoschi has initialized a light weight review process. This concentrates mostly on the machine and the physics, but there is also a sub groups reviewing the detector concepts SiD and ILD. This groups is lead by Paul Grannis and will have its first meeting during the LCWS2015 in Whistler. Ties thinks it will not be a strict review process, but in particular for the R&D groups the goal is to discuss and establish a common review process. This could be either a continuation of the ECFA R&D Detector panel or a similar global review panel. Paul was suggested as a representative of LCTPC. Jochen will ask, if he accepts.

The speaker's bureau will discuss the VCI abstracts next week. But Ties suggested that each group should send its own abstract, so that there is a higher pressure on the organizing committee to give at least one combined talk. This has worked in the past very well.

## News from the groups:

Ralf announced, that the DESY group is planning for a next test beam campaign – probably sometime in May. They a planning to test new modules where the ceramic frame design will be modified. Also the GEM stretching and gluing procedure shall be improved, so that the GEMs are flatter and more equal. The intention is to develop tools for the complete procedure and not use manual stretching to improve the flatness and ensure reproducible results. Also, the HV stability is studied currently and hopefully some improvements can be implemented. Finally, also a new pad plane is under discussion, but due to the short time, only small changes are under consideration.

### AOB:

The next workpackage meeting will take place on November 12<sup>th</sup>.